



# **DPS1035**

## 24V/3.5A 1-CH POWER SWITCH W/ REVERSE-VOLTAGE PROTECTION

# Description

The DPS1035 is part of a family of power switches optimized for the USB Type- $C^{\textcircled{R}}$  and other hot-swap applications. Through the analog interface, exception status is reported and functions like voltage limiting and output voltage ramp-up rate can be programmed.

This device is designed to operate between 4.5V and 24V. Its built-in fault-handling mechanism includes reverse voltage and current blocking, input over-voltage protection, and thermal shutdown. In addition, the ramp-up time of the output voltage can be adjusted to minimize in-rush current and to ensure system stability. Before any exception condition is notified via the low-active FAULTB signal, deglitch of 7ms is applied to prevent false triggering.

The DPS1035 is housed in the low-profile and space-saving V-QFN4040-17 package which is manufactured with environmentally friendly material.

# Features

- Wide Operating Voltage Range: 4.5V to 24V
- 1-Channel Power Switch with Built-In Fault Detection and Recovery Mechanisms like Input Under-Voltage Lockout, Reverse-Voltage and Current Blocking, Thermal Shutdown and Input Over-Voltage Protection
- RDS(ON) of Embedded Power MOSFET at 30mΩ
- Adjustable DV/DT Control at Start-Up
- Manual Discharge ON/OFF Control for IN and OUT Ports
- Fault Reporting (FAULTB) with Blanking Time at 7ms Typical
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

**Pin Assignments** 



# Applications

- Notebooks, desktops and AIO PCs; servers and tablets
- Docking stations, universal and multimedia hubs
  FPTVs, PC monitors
  - Set-Top boxes, residential gateways, storage devices

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 Halogen- and Antimony free, "Creen" products are defined as these which contains (2000ppm braning, 2000ppm chloring, (1500ppm total Br. (2)) and (1500ppm total Br. (3)) and (1500p

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



DPS1035

# **Typical Application Circuit**



# **Pin Descriptions**

	1				
Pin Number	Pin Name	Туре	Function		
1, 2, 3	IN	Р	Power Supply and Input Port.		
4	EN	_	Enable. '0' = device OFF; '1' = device ON. This pin must not be left floating.		
5, 11, 13	NC	4	No Connection. All NC pins must be left floating.		
6	GND	GND	Device Ground		
7	VREG	I/O	Voltage Regulator. A 0.1µF capacitor is recommended between this pin and ground.		
8	DISC1	f	N Port Discharge Control. '1' = port voltage to be discharged; '0' = disabled.		
9	DISC2	- I )	OUT Port Discharge Control. '1' = port voltage to be discharged; '0' = disabled.		
10	FAULTB	0	Fault Status Indicator. An external pull-up resistor is required. This active-low pin shall be tied to GND when not used.		
12	DV/DT	I/O	Ramp-up Control. A capacitor between this pin and GND sets the ramp-up rate.		
14	VLIM	1/0	Voltage Limit Setting. A resistor between this pin and GND sets the over-voltage limit of the IN port.		
15, 16, 17	OUT	0	Output Port.		
18 (Exposed Pad)	SRC	I/O	Common Source. The exposed pad of the V-QFN4040-17 package must not be connected to any signal.		



# **Functional Block Diagram**



# Absolute Maximum Ratings (@ TA = +25°C, unless otherwise specified.) (Note 4)

Symbol	Parameter	Rating	Unit
Vin, Vout	Voltage Range of IN and OUT Pins	-0.3 to 30	V
VI/O	Voltage Range of Others (EN, VREG, DISC1, DISC2, FAULTB, DV/DT and VLIM Pin)	-0.3 to 6	V
Ιουτ	Output Load Current Range	5	А
TJ	Operating Junction Temperature	-40 to +125	°C
TL	Lead Temperature	+260	°C
T <sub>ST</sub>	Storage Temperature	-65 to +150	°C
ESD	Human Body Model (HBM), JESD22-A114	2	
	Charge Device Model (CDM)	0.5	Κv

Note: 4. These are stress ratings only. Operation outside the absolute maximum ratings can cause device failure. Operation at the absolute maximum rating for extended periods can reduce device reliability.

# Thermal Characteristics (@ TA = +25°C, unless otherwise specified.) (Note 5)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	2.1	W
Reja	Thermal Resistance, Junction-to-Ambient	58.5	°C/W
Rejc	Thermal Resistance, Junction-to-Case	9.4	°C/W

Note: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1"x1" copper pad layout.



# Recommended Operating Conditions (@ TA = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
Vin	Input Supply Voltage	4.5	24	V
Vout	Output Voltage	0	24	V
IOUT	Output Load Current	0	3.5	А
CIN	Input Capacitance	1	_	μF
Соит	Output Capacitance	1		μF
VEN	Input Voltage on EN	0	5	V
VDISC1, VDISC2	Input Voltage on DISC1 and DISC2	0	5.5	V

# **Electrical Characteristics**

 $(@T_{A} = +25^{\circ}C, V_{IN} = 4.5V \text{ to } 24V, C_{IN} = C_{OUT} = 10 \mu F, V_{EN} = 3.3V, C_{DV/DT} = 1nF, R_{VLIM} = 240 k\Omega, unless otherwise specified.)$ 

Symbol	Parameter	Condition	Min	Тур	Max	Unit	
Bias Supply	Bias Supply						
Vuvlo	VIN Under-Voltage Lockout Threshold	V <sub>IN</sub> Rising	3.2	3.7	4	V	
Vuvhy	VIN Under-Voltage Lockout Threshold Hysteresis	V <sub>IN</sub> Falling		250	_	mV	
		$V_{IN} = 5V, V_{EN} = 0V$		_	10		
ISHDN	Shutdown Current (Disabled)	$V_{IN} = 12V, V_{EN} = 0V$	—	—	25	μA	
		$V_{IN} = 20V, V_{EN} = 0V$	—	—	50		
		V <sub>IN</sub> = 5V, No Load	_	_	3		
lq	Quiescent Current (Enabled)	V <sub>IN</sub> = 12V, No Load	—	—	4	mA	
		VIN = 20V, No Load	_	_	4.5		
Enable Contro	ol						
VENL	EN Threshold Voltage Low	Ven Falling	—	—	0.4	V	
Venh	EN Threshold Voltage High	VEN Rising	1.4	_		V	
IEN	EN Input Leakage Current	$V_{IN} = 5V, V_{EN} = 5V$	—	_	1	μA	
Over-Voltage	Protection						
Ivlim	VLIM Sourcing Current	$V_{IN} = 5V, R_{VLIM} = 57.6k\Omega$	—	10	_	μA	
Rvlim_max	Maximum RvLIM	-	_	_	300	kΩ	
	Input Over-Voltage Threshold,	$R_{VLIM} = 57.6k\Omega$ , $V_{IN}$ Rising	—	6		V	
VOVPRTH	Rising	$R_{VLIM} = 240 k\Omega$ , $V_{IN}$ Rising	_	24	_		
	Input Over-Voltage Threshold,	$R_{VLIM} = 57.6k\Omega$ , $V_{IN}$ Falling	_	5.6			
VOVPFTH	Falling	$R_{VLIM} = 240 k\Omega$ , $V_{IN}$ Falling	_	23.6		1	
MOSFET							
		VIN = 5V, IOUT = 1A	—	30	40	mΩ	
RDS(ON)	Switch ON Resistance	VIN = 12V, IOUT = 1A	—	30	40		
		VIN = 20V, IOUT = 1A	—	30	40		
Ilkgsrc	OUT Leakage Current in OFF State, Sourcing	$V_{EN} = 0V$ , $V_{OUT} = 0V$	—	_	1	μA	
		VIN = 3.3V, VEN = 0V, VOUT = 5V	—	—	1		
Ilkgsnk	OUT Leakage Current in OFF State Sinking	VIN = 3.3V, VEN = 0V, VOUT = 12V	_	_	1	μA	
	State, Sinking	$V_{IN} = 3.3V, V_{EN} = 0V, V_{OUT} = 20V$	—	_	1	1	
Reverse-Voltage Protection							
Vrvpfth	V <sub>IN</sub> - V <sub>OUT</sub> Threshold Entering into Reverse Protection	VIN - VOUT Falling	—	-40	_	m\/	
Vrvprth	VIN - VOUT Threshold Exiting from Reverse Protection	V <sub>IN</sub> - V <sub>OUT</sub> Rising	-15	0	_	111 V	
<b>t</b> RVPTD	Reverse Protection Response Time	_	_	_	2	μs	



# Electrical Characteristics (continued)

 $(@T_{A} = +25^{\circ}C, V_{IN} = 4.5V \text{ to } 24V, C_{IN} = C_{OUT} = 10 \mu F, V_{EN} = 3.3V, C_{DV/DT} = 1nF, R_{VLIM} = 240 k\Omega, unless otherwise specified.)$ 

Symbol	Parameter	Condition	Min	Тур	Max	Unit	
Output Ramping Control							
Idv/dt	DV/DT Sourcing Current	V <sub>DV/DT</sub> = 0V		1		μA	
G <sub>DV/DT</sub>	DV/DT to OUT Gain	$\Delta V_{OUT} / \Delta V_{DV/DT}$ , Guaranteed by Design		12		V/V	
Output Timing	g	·					
		$V_{IN} = 5V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 0V$ to $2V$		0.2		ms	
<b>t</b> DON	Output Turn-ON Delay Time	$V_{IN} = 12V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 0V$ to $2V$	—	0.2	_		
		$V_{IN} = 20V, C_{OUT} = 1\mu F, V_{EN} = 0V \text{ to } 2V$		0.2	_		
		$V_{IN} = 5V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 0V$ to $2V$		0.3	-		
tR	Output Turn-ON Rise Time	$V_{IN} = 12V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 0V$ to $2V$	Ì	0.8	_	ms	
		$V_{IN} = 20V, C_{OUT} = 1\mu F, V_{EN} = 0V \text{ to } 2V$		1.6			
		$V_{IN} = 5V$ , $C_{OUT} = 1\mu$ F, $V_{EN} = 2V$ to 0V	_	1	-		
<b>t</b> DOFF	Output Turn-OFF Delay Time	$V_{IN} = 12V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 2V$ to $0V$	-	2		μs	
		VIN = 20V, COUT = 1µF, VEN = 2V to 0V	-	4	_		
	Output Turn-OFF Fall Time	$V_{IN} = 5V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 2V$ to $0V$		10			
tF		$V_{IN} = 12V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 2V$ to $0V$		25	_	μs	
		$V_{IN} = 20V$ , $C_{OUT} = 1\mu F$ , $V_{EN} = 2V$ to $0V$		50	_		
Discharge Co	ntrol on IN/OUT Pins			*			
		VDISC1 = 5V, VDISC2 = 5V	_	70	—	Ω	
RDISC1/DISC2	IN/OUT Discharge Resistance	VDISC1 = 3.3V, VDISC2 = 3.3V	_	82	_	Ω	
Vdisc1l/ Vdisc2l	DISC1/DISC2 Threshold Voltage Low	VDISC1/VDISC2 Falling	_	_	0.4	V	
Vdisc1h/ Vdisc2h	DISC1/DISC2 Threshold Voltage High	VDISC1/VDISC2 Rising	1.4	_	_	V	
Fault Flag (FAULTB): Active Low							
RFAULTB	FAULTB Pull-Down Resistor	$V_{IN} = 7V$ , $R_{VLIM} = 57.6k\Omega$ , $I_{FAULTB} = 10mA$ Sinking	_	25	_	Ω	
ILKGFAULTB	FAULTB Leakage Current	$V_{IN} = 5V, R_{VLIM} = 57.6 k\Omega, V_{FAULTB} = 5V$		_	1	μA	
<b>t</b> BLANKFAULTB	FAULTB Blanking Time	$V_{IN} = 5V, R_{VLIM} = 57.6 k\Omega, V_{FAULTB} = 5V$		7	_	ms	
Thermal Shutdown							
T <sub>SHDN</sub>	Thermal Shutdown Threshold	-		+155		•	
THYS	Thermal Shutdown Hysteresis	-		+20			



# **Performance Characteristics**

 $(@T_{A} = +25^{\circ}C, C_{IN} = C_{OUT} = 10 \mu F, V_{EN} = 3.3V, C_{DV/DT} = 1nF, R_{VLIM} = 240 k\Omega, unless otherwise specified.)$ 



EN Turn ON and In-Rush Current at 20V  $V_{IN} = 20V, R_{LOAD} = 100\Omega, C_{OUT} = 100\mu F, C_{DV/DT} = 10nF$ 









EN Turn OFF with a 5.6 $\Omega$  Load at 20V







# **Application Information**

### **General Description**

The DPS1035 is a unidirectional power switch designed to meet the input and output voltage/current requirement which is common with many hotpluggable serial interfaces found in the computing and consumer electronics equipment.

### Ramp-Up Time and In-Rush Current Control

An external capacitor connected from the DV/DT pin to GND defines the slew rate of the output voltage at power-on:

dVout / dt = (I<sub>DV/DT</sub> / C<sub>DV/DT</sub>) × G<sub>DV/DT</sub>, where I<sub>DV/DT</sub> =1 $\mu$ A typ. and G<sub>DV/DT</sub> = 12

The total ramp-up time  $t_{DV/DT}$  of V<sub>OUT</sub>, increasing from 0 to V<sub>IN</sub>, can be calculated using the following equation:

 $t_{DV/DT} = 8.3 \times 10^4 \times V_{IN} \times C_{DV/DT}$ 

The in-rush current at power-up shall be limited by the regulated output voltage ramp.

### Input Over-Voltage Protection (OVP)

The voltage at the IN port is monitored continuously. Whenever voltage at the IN port is found to be larger than the VOVPRTH value, the built-in over-voltage protection (OVP) fault-handling mechanism is triggered. The internal power MOSFET will be turned OFF to protect the downstream equipment connected. The VOVPRTH value is determined by:

VOVPRTH =  $0.1 \times \text{RvLim}$ , where the unit of RvLim is k $\Omega$  and  $51k\Omega \leq \text{RvLim} \leq 240k\Omega$ .

### **Over-Temperature Protection (OTP)**

When the junction temperature T<sub>J</sub> reaches the thermal shutdown threshold  $T_{SHDN}$ , the internal power MOSFET would be turned OFF. The internal power MOSFET will be turned ON again once the condition [T<sub>J</sub> < (T<sub>SHDN</sub> - T<sub>HYS</sub>)] becomes valid.

### **Reverse-Voltage Protection (RVP)**

The voltage difference,  $[V_{IN} - V_{OUT}]$ , between the IN and OUT ports is monitored continuously. Once the voltage difference drops below the VRVPFTH level, the device shall immediately turn OFF the internal power MOSFET to prevent the current flowing from the opposite direction. When the reverse-voltage condition is no longer valid, i.e.  $[V_{IN} - V_{OUT}]$  becomes greater than the VRVPRTH level, the internal power MOSFET shall be turned ON.

### Fault Response

An external pull-up resistor is required. The device generates a warning flag whenever one of the following fault conditions becomes valid: input over-voltage, reversed-voltage, over-temperature. After a de-glitch time-out of 7ms, the low-active FAULTB signal shall be asserted. The FAULTB signal shall remain 'low' and the internal power MOSFET remains OFF until the exception status is no longer valid.

### **Discharge Function**

To facilitate the various applications envisioned by the system designers, the IN and OUT ports can be discharged via two external controls: DISC1, DISC2. The internal discharge resistor is around 80Ω. The settings are shown in the table below.

DISC1	DISC2	Description
0	0	Discharge function disabled
0	1	OUT Port is being discharged until the pin DISC2 is pulled 'low'
1	0	IN Port is being discharged until the pin DISC1 is pulled 'low'
1	1	Both IN and OUT ports are discharged simultaneously



# Application Information (continued)

### **PCB Layout Consideration**

- 1. Place the input and output capacitors, CIN and COUT, as close as possible to the IN and OUT pins.
- 2. The power traces, including the power ground, the V<sub>IN</sub> trace and the V<sub>OUT</sub> trace should be kept direct, short and wide.
- 3. Place the resistors and capacitors (RvLIM, CDV/DT and CVREG) as close as possible to the corresponding device pins.
- 4. Connect the signal ground to the GND pin, and keep a single connection from GND pin to the power ground behind the input capacitor.
- 5. For better power dissipation, via holes are recommended to connect the exposed pad's landing area to a large copper polygon on the other side of the printed circuit board. The copper polygons and exposed pad of SRC (common source nodes of internal power MOSFET) shall not be connected to any of the signal and power grounds on the printed circuit board.





# **OBSOLETE – PART DISCONTINUED**





# Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.500
G	0.150
Х	0.350
X1	1.350
X2	2.975
X3	2.850
X4	3.825
X5	1.300
Y	0.600
Y1	2.350
Y2	2.600
Y3	4.300
Y4	1.300

# **Mechanical Data**

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (2014)
- Weight: 0.041 grams (Approximate)



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